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Amendments to the Claims:

1. (Currently Amended) A method for verifying reticle enhancement technique latent post-

optical proximity corrected mask wafer image sensitivity to mask reticle manufacturing errors,

said method comprising: revising a polygon based on mask CD distributions to provide

statistically modifying layout polygons based on reticle critical dimension specifications to

construct a virtual statistical virtual mask; obtaining response function statistical parameters

based on the virtual mask image response function statistical parameters; and comparing the

statistical parameters to design rule process tolerance requirements.

2. (Currently Amended) A method as recited in claim 1, further comprising forming an a

simulated image of the statistical virtual mask.

3. (Currently Amended) A method as recited in claim 2, further comprising calculating

response functions based on the acrial and/or latent image simulation simulated image.

4. (Currently Amended) A method as recited in claim 3, further comprising collecting

measurements simulated image critical dimensions and calculating statistical parameters based

on the response functions.

5. (Currently Amended) A method as recited in claim 4, further comprising comparing the

statistical parameters with design rule simulated wafer critical dimension distributions with

process tolerance requirements.

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6. (Currently Amended) A method as recited in claim 1, further comprising obtaining the

statistical virtual mask by using mask reticle critical dimension CD distribution specifications to

induce reticle manufacturing statistical variations to layouts which have passed through an OPC

optical proximity correction procedure.

7. (Currently Amended) A method as recited in claim 6, further comprising at least one of

moving fragments of a polygon and re-sizing primitives of a post-optical proximity correction

polygon.

8. (Currently Amended) A method as recited in claim 6, further comprising moving

fragments of a post-optical proximity correction polygon based on a randomly generated number

from mask CD distribution a reticle critical dimension specification.

9. (Currently Amended) A method as recited in claim 6, further comprising re-sizing

primitives depending on mask CD distribution a reticle critical dimension specification.

10. (Currently Amended) A yield prediction tool for mask quality specifications, said tool

comprising means for revising a polygon based on mask CD distributions to provide statistically

modifying layout polygons based on reticle critical dimension specifications to construct a

statistical virtual mask, means for obtaining statistical parameters based on the virtual mask

imaging response function statistical parameters; and means for comparing the statistical

response parameters to design rule process tolerance requirements.

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11. (Currently Amended) A tool as recited in claim 10, further comprising means for

simulating an aerial and/or latent image of the statistical formed virtual mask.

12. (Original) A tool as recited in claim 11, further comprising means for calculating

response functions based on the simulated image.

13. (Currently Amended) A tool as recited in claim 12, further comprising means for

collecting measurements simulated image critical dimensions and calculating statistical

parameters based on the response functions.

14. (Currently Amended) A tool as recited in claim 13, further comprising means for

comparing the statistical parameters with design rule simulated wafer critical dimension

distributions with process tolerance requirements.

15. (Currently Amended) A tool as recited in claim 10, further comprising means for

obtaining the statistical virtual mask by using mask riticle critical dimension CD distribution

specifications to statistically vary layouts which have passed through an OPC optical proximity

correction procedure.

16. (Currently Amended) A tool as recited in claim 15, further comprising means for at least

one of moving fragments of a polygon and re-sizing primitives of a post-optical proximity

correction polygon.

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17. (Currently Amended) A tool as recited in claim 15, further comprising means for moving fragments of a <u>post-optical proximity correction</u> polygon based on a randomly generated number from <u>mask CD distribution a reticle critical dimension specification</u>.

18. (Currently Amended) A tool as recited in claim 15, further comprising means for resizing primitives depending on mask CD distribution a reticle critical dimension specification.

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